

Customer No.: 31561  
Application No.: 10/605,034  
Docket No.: 10231-US-PA

**In The Claims**

**Claims 1-8. (cancelled)**

Claim 9. (previously presented) A chip package structure, comprising:

a substrate;

a chip, disposed on the substrate and electrically connected to the substrate;

a stiffener, disposed above and unattached to the substrate, wherein the stiffener includes an outer surface and an opposite inner surface and the inner surface of the stiffener faces the substrate, and wherein the stiffener has at least an opening and the chip is completely exposed by the opening; and

a molding compound, covering the chip, the matrix substrate, the outer surface and the inner surface of the stiffener.

**Claims 10-11. (cancelled)**

Claim 12. (original) The chip package structure of claim 9, wherein the chip package structure further includes a plurality of wires and the chip disposed on the substrate is electrically connected to the substrate through the wires.

Claim 13. (original) The chip package structure of claim 9, wherein a material of the stiffener is copper.

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**Claim 14. (previously presented)** A chip package structure, comprising:

a thin substrate, wherein the thin substrate has a thickness of between about 0.1mm and about 0.5 mm;

a chip, disposed on the thin substrate and electrically connected to the thin substrate;

a stiffener, disposed above and unattached to the thin substrate, and wherein the stiffener has at least an opening and the chip is completely exposed by the opening; and

a molding compound, covering the chips, the thin substrate and the stiffener.

**Claim 15. (original)** The chip package structure of claim 14, wherein the stiffener includes an outer surface and an opposite inner surface and the inner surface of the stiffener faces the thin substrate and the molding compound covers the inner surface and the outer surface of the stiffener.

**Claims 16-17. (cancelled)**

**Claim 18. (original)** The chip package structure of claim 14, wherein the chip package structure further includes a plurality of wires and the chip disposed on the substrate is electrically connected to the substrate through the wires.

**Claim 19. (original)** The chip package structure of claim 14, wherein a material of the stiffener is copper.

**Claims 20-23. (cancelled)**